GENNEL GN109-75

GENNEL G109 75g Thermal Glue Instruction Manual

Model: GN109-75

1. Product Overview

The GENNEL G109 75g Thermal Glue is a high-performance silicone viscous adhesive compound designed for effective heat transfer and secure bonding in electronic components. It functions as a thermal conductive plaster, suitable for applications requiring both thermal conductivity and strong adhesion.

This product is ideal for use with LEDs, GPUs, chipsets, printers, MOSFETs, and various heatsink cooling and sealing applications. Its non-electrical conductive, non-corrosive, and non-toxic properties ensure safe and reliable performance.



Image 1.1: GENNEL G109 75g Thermal Glue tube.

2. Safety Information

- **Important:** Do not use this thermal glue between a CPU and its heatsink. This product creates a permanent bond and is not intended for components that require regular removal or non-permanent thermal interface material.
- Avoid direct contact with skin and eyes. In case of contact, rinse thoroughly with water. If irritation persists, seek medical attention.
- Use in a well-ventilated area to prevent inhalation of fumes.
- Keep out of reach of children and pets.
- Store in a cool, dry place, away from direct sunlight and heat sources.



Image 2.1: Safety icon indicating non-electrical conductivity.

3. Product Features

- **Non-Electrical Conductive:** Safe for use in electronic assemblies without risk of short circuits.
- **Non-Corrosive & Non-Toxic:** Ensures component longevity and user safety.
- **Strong Adhesion:** Provides a durable and secure bond for heatsinks and components.
- **High Thermal Conductivity:** > 1.5W/m-K, effectively dissipating heat.
- **Wide Operating Temperature Range:** Stable performance from -60°C to 280°C (-76°F to 536°F).
- **Fast Surface Drying:** Initial drying in 5-15 minutes.
- **Versatile Application:** Suitable for MOSFETs, LEDs, chipsets, video cards, and various heat dissipation parts.

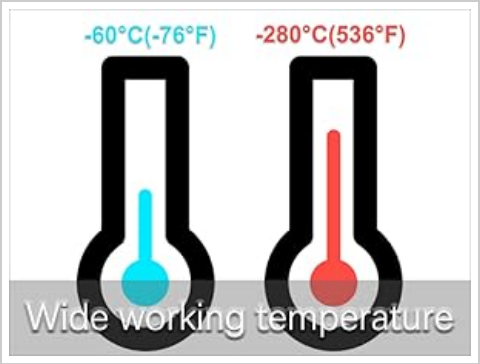


Image 3.1: Icon illustrating wide working temperature range.

4. Setup and Application

1. **Prepare Surfaces:** Ensure all surfaces to be bonded are clean, dry, and free from dust, oil, or other contaminants. Use isopropyl alcohol for cleaning if necessary.
2. **Apply Glue:** Dispense a small, even amount of GENNEL G109 Thermal Glue onto one of the surfaces. Avoid excessive application.
3. **Position Component:** Carefully place the heatsink or component onto the glued surface, ensuring proper alignment and firm contact.
4. **Allow to Cure:** The glue will begin to surface dry in 5-15 minutes. Allow a full cure time of 24 hours for maximum adhesion and thermal performance. Avoid disturbing the bonded components during the curing period.



Image 4.1: Application steps for GENNEL G109 Thermal Glue.

5. Operating Instructions

Once the GENNEL G109 Thermal Glue has fully cured (after 24 hours), the bonded components are ready for operation. The glue provides a stable and permanent thermal interface, effectively transferring heat away from the electronic component to the heatsink.

This product is designed for applications where a permanent bond is desired. It is not intended for use as a temporary thermal paste that can be easily removed.



Image 5.1: Wide range of applications for GENNEL G109 Thermal Glue.

6. Maintenance

Once applied and fully cured, the GENNEL G109 Thermal Glue requires no ongoing maintenance. Its long-lasting and stable performance ensures continuous thermal transfer.

For storage of unused glue, ensure the tube cap is tightly sealed to prevent drying. Store in a cool, dry environment away from direct sunlight.

7. Troubleshooting

- **Poor Adhesion:** Ensure surfaces were thoroughly cleaned and dried before application. Verify that sufficient glue was applied and that the components were held firmly in place during initial drying. Allow the full 24-hour cure time.
- **Ineffective Heat Transfer:** Confirm that the glue was applied evenly and created good contact between the component and the heatsink. Ensure the heatsink itself is adequately sized for the heat load.
- **Accidental Skin/Eye Contact:** Refer to the Safety Information section (Section 2) for immediate actions.

8. Specifications

Specification	Value
Model	GN109-75
Brand	GENNEL
Net Weight	75g
Full Cure Time	24 Hours
Surface Drying Time	5-15 minutes
Evaporation	0.001% (280°C / 24H)
Insulation Coefficient	> 5.1
Dissipation Coefficient	< 0.005
Thermal Conductivity	> 1.5W/m-K
Operating Temperature	-60°C to 280°C (-76°F to 536°F)
Adhesion and Tensile Strength	2.1 MPa (2.1 Pounds Per Square Inch)
Non-Electrical Conductive	Yes
Material	Silicone
Item Form	Paste
Container Type	Tube
Water Resistance Level	Not Water Resistant
Compatible Material	Aluminum, Copper, Metal, Plastic
Volume	50 Milliliters (2.6456 Ounce)
Color	White
UPC	751474301871

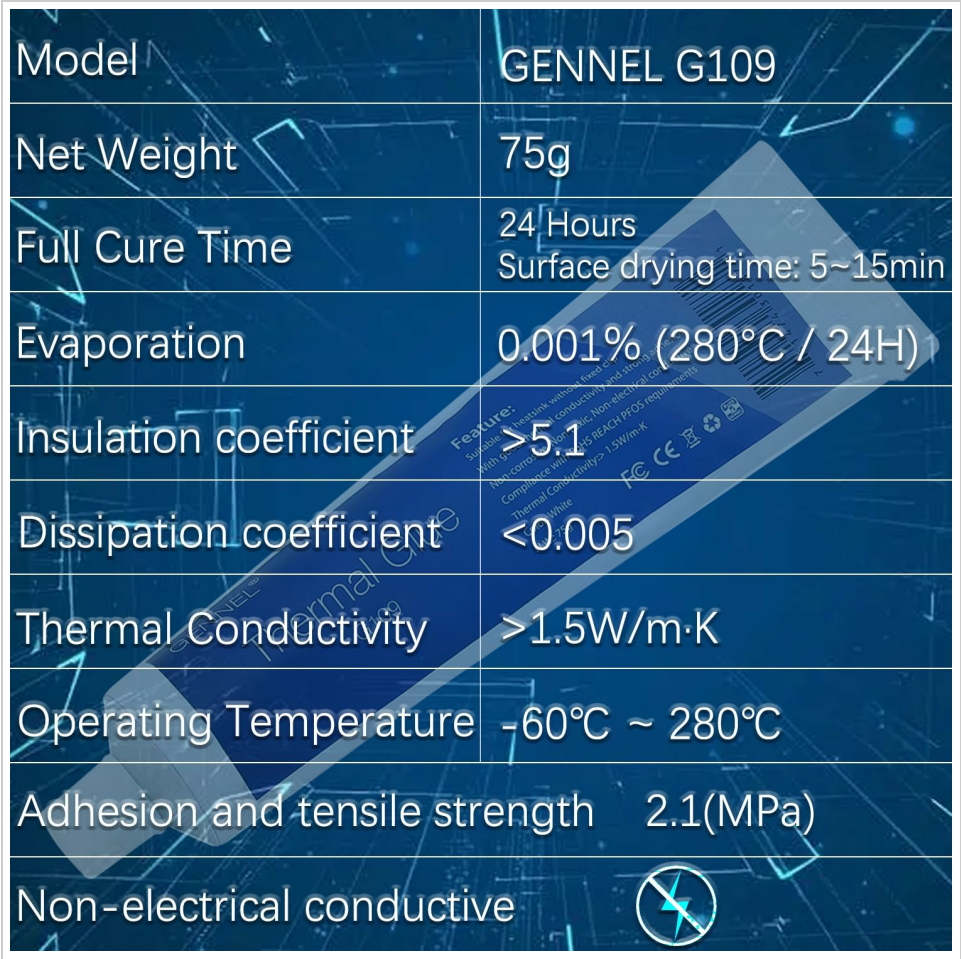


Image 8.1: Detailed specifications for GENNEL G109 Thermal Glue.

9. Warranty and Support

Specific warranty information for the GENNEL G109 75g Thermal Glue is not provided in this manual. Please refer to the product packaging or contact the manufacturer directly for warranty details.

For further assistance, technical support, or inquiries, please contact GENNEL customer service through their official website or the retailer where the product was purchased.

Manufacturer: GENNEL

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